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April 1<sup>st</sup>, 2010  
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## HD151TS207SS

### Mother Board Clock Generator for Intel P4+ Chipset (Springdale)

REJ03D0006-0100Z  
Preliminary  
Rev.1.00  
Apr.25.2003

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#### Description

The HD151TS207SS is Intel CK409T type high-performance, low-skew, low-jitter, PC motherboard clock generator. It is specifically designed for Intel Pentium<sup>®</sup> 4+ chipset.

#### Features

- 3 differential pairs of current mode control CPU clocks
- 1 differential pair of Serial Reference Clock (SRC), selectable 100 MHz/200 MHz
- 6 copies PCI clocks and 3 copies PCIF clocks @3.3V, 33.3 MHz
- 1 copy PCI clock @3.3 V, selectable 33.3 MHz/25 MHz
- 1 copy USB clock @3.3 V, selectable 48 MHz/24 MHz
- 1 copy DOT clock @3.3 V, 48 MHz
- 4 copies of 3V66 clocks @3.3 V, 66.6 MHz
- 1 copy of 3V66/VCH clock @3.3 V, selectable 66.6 MHz/48 MHz
- 2 copies of REF clocks @3.3 V, 14.318 MHz
- Power save and clock stop function
- I<sup>2</sup>C<sup>™</sup> serial port programming
- Programmable Clock Control (Spread Spectrum Percentage, Clock Output Skew, Slew Rate)
- Watchdog timer and reset output
- 56pin SSOP (300 mils)

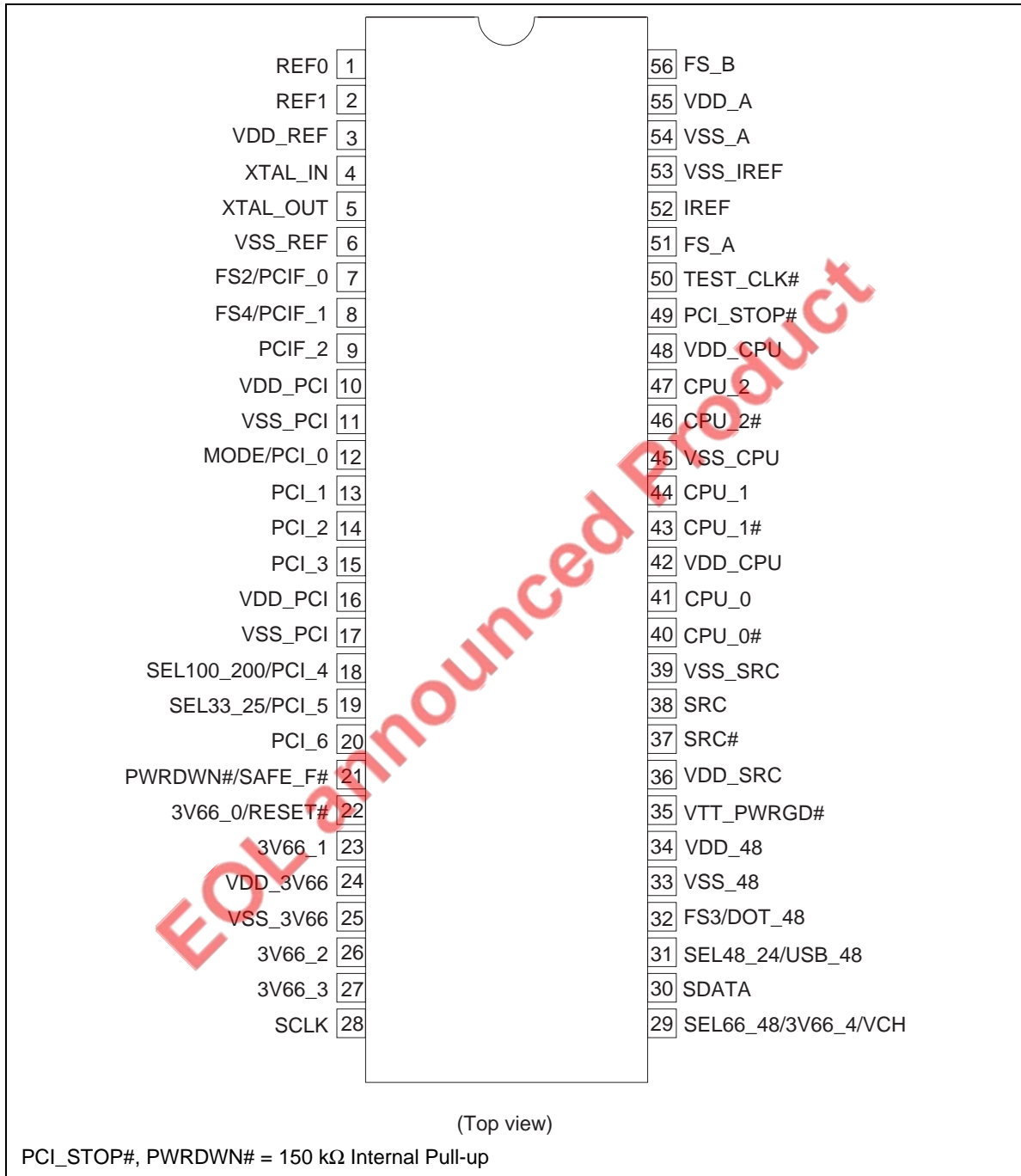
Note: I<sup>2</sup>C is a trademark of Philips Corporation.  
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**Key Specifications**

- Supply Voltages: VDD = 3.3 V $\pm$ 5%
- CPU clock cycle to cycle jitter = |125ps| (SSC Disabled)
- CPU clock group Skew = 100ps
- 3V66 clock group Skew = 250psmax
- PCI clock group Skew = 500psmax

**EOL announced Product**

**Pin Arrangement**



## HD151TS207SS

### Pin Descriptions

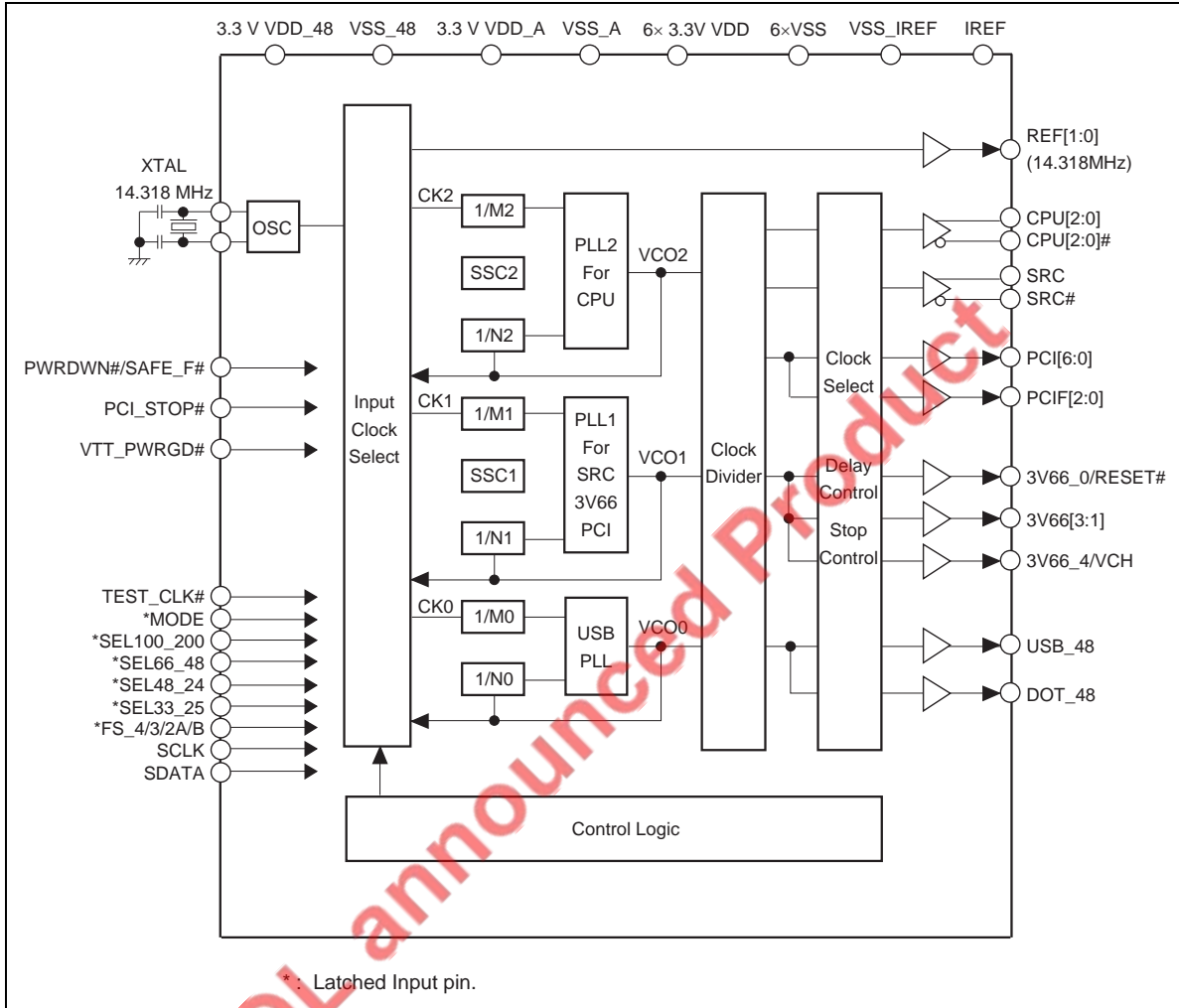
Pin name	No.	Type	Description
VSS_A	54	Ground	Ground for PLL
VSS_CPU	45		Ground for outputs
VSS_IREF	53		Ground for current reference
VSS_SRC	39		Ground for outputs
VSS_3V66	25		
VSS_PCI	11, 17		
VSS_REF	6		
VSS_48	33		
VDD_A	55	Power	3.3 V Power Supply for PLL
VDD_CPU	42, 48		3.3 V Power Supply for outputs
VDD_SRC	36		
VDD_3V66	24		
VDD_PCI	10, 16		
VDD_REF	3		
VDD_48	34		
REF0	1	OUTPUT	3.3 V 14.318 MHz reference clock.
REF1	2		
XTAL_IN	4	INPUT	14.318 MHz XTAL input.
XTAL_OUT	5	OUTPUT	14.318 MHz XTAL output. Don't connect when an external clock is applied at XTAL_IN.
FS2/PCIF_[0:1]	7,8	INPUT/ OUTPUT	Frequency select latch input pin. /Free running PCI clock 3.3 V output.
PCIF_2	9	OUTPUT	Free running PCI clock 3.3 V output.
**MODE/PCI_0	12	INPUT/ OUTPUT	Function select latch input pin for pin 22, 1 = Reset#, 0 = clock output. /PCI clock 3.3 V output.
PCI_[1:3]	13,14, 15	OUTPUT	PCI clock 3.3 V outputs.
**SEL100_200/ PCI_4	18	INPUT/ OUTPUT	Latched select input for SRC output. 1 = 200 MHz, 0 = 100 MHz /PCI clock 3.3 V output.
**SEL33_25/PCI_5	19	INPUT/ OUTPUT	Latched select input for PCI5 output. 1 = 25 MHz, 0 = 33 MHz /PCI clock 3.3 V output.
PCI_6	20	OUTPUT	PCI clock 3.3 V outputs.
Note:	(*):	Those pins are 150 k $\Omega$ internal pulled-UP.	
	(**):	Those pins are 150 k $\Omega$ internal pulled-DOWN.	

**Pin Descriptions (cont.)**

Pin name	No.	Type	Description
PWRDWN#/ SAFE_F#	21	INPUT PULL-UP*	PWRDWN# / SAFE_F# selectable input. Default is PWRDWN# input. Byte15[5] = "1" : SAFE_F# input. PWRDWN# is all clocks stop pin. Asynchronous active "Low" input. When asserted low, all output clocks are disabled. SAFE_F# is active "Low" input. When SAFE_F# is "Low", frequency mode is changed to the predefined frequency mode.
3V66_0/RESET#	22	OUTPUT	3V66 / Watchdog RESET# selectable output. Default is 3V66 output. This signal is active low and selected by Mode latch input.
3V66_[1:3]	23,26, 27	OUTPUT	3V66 clock 3.3V outputs.
SCLK	28	INPUT PULL-UP*	Clock input for I <sup>2</sup> C logic.
**SEL66_48/ 3V66_4/VCH	29	INPUT/ OUTPUT	Latched select input for 3V66/VCH output 1 = 48 MHz, 0 = 66.66 MHz. /3V66 or VCH clock output.
SDATA	30	IN/OUTPUT PULL-UP*	Data input for I <sup>2</sup> C logic.
**SEL48_24/ USB_48	31	INPUT/ OUTPUT	Latched select input for 48_24 MHz output 1 = 24 MHz, 0 = 48 MHz / 24_48 MHz clock 3.3 V output.
FS3/DOT_48	32	INPUT/ OUTPUT	Frequency select latch input pin. /DOT_48 clock 3.3 V output.
VTT_PWRGD#	35	INPUT PULL-UP*	Qualifying input that latches FS_A and FS_B. When asserted low, FS_A and FS_B are latched.
SRC#	37	OUTPUT	"Complementary" clock of Differential Serial Reference Clock.
SRC	38	OUTPUT	"True" clock of Differential Serial Reference Clock.
CPU_[0:2]#	40,43, 46	OUTPUT	"Complementary" clock of differential CPU clock.
CPU_[0:2]	41,44, 47	OUTPUT	"True" clock of differential CPU clock.
PCI_STOP#	49	INPUT PULL-UP*	PCI clocks stop pin. Active "Low" input. When asserted low, PCI[6:0] and SRC clocks are synchronously disabled in low state. Usually this pin does not give to effect PCIF[2:0] clock outputs.
TEST_CLK#	50	INPUT PULL-UP*	Test clock mode pin. Active "Low" input.
FS_[A:B]	51,52	INPUT	CPU clocks frequency select latch input.
IREF	52	INPUT	A precision resistor is attached to this pin which is connected to internal current reference. A resistor is connected between this pin and GNDIREF.

Note: (\*): Those pins are 150 kΩ internal pulled-UP.  
(\*\*): Those pins are 150 kΩ internal pulled-DOWN

Block Diagram





## I<sup>2</sup>C Controlled Register Bit Map

### Byte0 Control Register

Bit	Description	Contents	Type	Default	Note
7	Reserved		R	0	
6	Reserved		R	0	
5	Reserved		R	0	
4	Reserved		R	0	
3	PCI_Stop Reflects the current value of the external PCI_STOP# pin	0 = PCI_STOP# pin is Low 1 = PCI_STOP# pin is High	R	X	
2	Reserved		R	X	
1	FS_B Reflects the value of the FS_B pin sampled on power up	0 = FS_B Low at power up 1 = FS_B High at power up	R	X	See Table 1
0	FS_A Reflects the value of the FS_A pin sampled on power up	0 = FS_A Low at power up 1 = FS_A High at power up	R	X	

Table1 Clock Frequency Function Table

Byte6 Bit5	FS_A	FS_B	CPU [MHz]	SRC [MHz]	3V66 [MHz]	PCIF PCI [MHz]	REF0 REF1 [MHz]	USB DOT [MHz]	Note
0	0	0	100	100/200	66	33	14.318	48	
0	0	1	200	100/200	66	33	14.318	48	
0	1	0	133	100/200	66	33	14.318	48	
0	1	1	166	100/200	66	33	14.318	48	
1	0	0	200	100/200	66	33	14.318	48	
1	0	1	400	100/200	66	33	14.318	48	
1	1	0	266	100/200	66	33	14.318	48	
1	1	1	333	100/200	66	33	14.318	48	

Table2 Test Clock select table

TEST_CLK#	CPU [MHz]	SRC [MHz]	3V66 [MHz]	PCIF PCI [MHz]	REF0 REF1 [MHz]	USB DOT [MHz]	Note
1	REF/2	REF/2	REF/4	REF/8	REF	REF/2	See Note1, Table3
0	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	

Note: 1. REF is a clock over driven on the XIN during test mode.

**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Table3 FS\_A and FS\_B pin Input level

Logic Level	Min Voltage	Max Voltage
0 (Low)	—	0.35V
1 (High)	0.70V	—

Byte1 Control Register

Bit	Description	Contents	Type	Default	Note
7	Allow control of SCR with assertion of PCI_STOP#	0 = Free running 1 = Stopped with PCI_STOP#	RW	0	See Table5
6	SRC Output enable	0 = Disabled (tristate) 1 = Enabled	RW	1	
5	Reserved		RW	1	
4	Reserved		RW	1	
3	Reserved		RW	1	
2	CPU2 Output enable	0 = Disabled (tristate) 1 = Enabled	RW	1	
1	CPU1 Output enable	0 = Disabled (tristate) 1 = Enabled	RW	1	
0	CPU0 Output enable	0 = Disabled (tristate) 1 = Enabled	RW	1	

Byte2 Control Register

Bit	Description	Contents	Type	Default	Note
7	SRC_Pwrdsn drive mode	0 = Driven in power down, 1 = Tristate	RW	0	See Table5
6	SRC_Stop drive mode	0 = Driven when stopped, 1 = Tristate	RW	0	
5	CPU2_Pwrdsn drive mode	0 = Driven in power down, 1 = Tristate	RW	0	See Table4
4	CPU1_Pwrdsn drive mode	0 = Driven in power down, 1 = Tristate	RW	0	
3	CPU0_Pwrdsn drive mode	0 = Driven in power down, 1 = Tristate	RW	0	
2	Reserved		RW	0	
1	Reserved		RW	0	
0	Reserved		RW	0	

**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Table4 CPU Clock Power Management Truth Table

Signal	Pin PWRDWN#	PWRDWN# Tristate Bit Byte2[5:3]	Non-Stop Outputs Byte1[5:3] = 1	Note
CPU[2:0]	1	X	Running	
CPU[2:0]	0	0	Driven @ Iref x2	See Note1
CPU[2:0]	0	1	Tristate	

Note: 1. Iref = VDD/(3Rr) = 3.3/(3x475) = 2.32 mA,  
Iref x2 = 4.6 mA (Voh @Z: 0.23 V @50 Ω)

Table5 SRC Clock Power Management Truth Table

Signal	Pin PWRDWN#	Pin PCI_STOP#	PCI_STOP# Tristate Bit Byte2[6]	PWRDWN# Tristate Bit Byte2[7]	Non-Stop Outputs Byte1[7] = 1	Stoppable Outputs Byte1[7] = 0	Note
SRC	1	1	X	X	Running	Running	
SRC	1	0	0	X	Running	Driven @ Iref x6	See Note1
SRC	1	0	1	X	Running	Tristate	
SRC	0	X	X	0	Driven @ Iref x2	Driven @ Iref x2	See Note1
SRC	0	X	X	1	Tristate	Tristate	

Note: 1. Iref = VDD/(3Rr) = 3.3/(3x475) = 2.32 mA  
Iref x6 = 13.9 mA (Voh @Z: 0.7 V @50 Ω)  
Iref x2 = 4.6 mA (Voh @Z: 0.23 V @50 Ω)

Byte3 Control Register

Bit	Description	Contents	Type	Default	Note
7	PCI_Stop control	0 = Enabled, all stoppable PCI and SRC clocks are stopped. 1 = Disabled	RW	1	
6	PCI_6 Output enable	0 = Disabled, 1 = Enabled	RW	1	
5	PCI_5 Output enable	0 = Disabled, 1 = Enabled	RW	1	
4	PCI_4 Output enable	0 = Disabled, 1 = Enabled	RW	1	
3	PCI_3 Output enable	0 = Disabled, 1 = Enabled	RW	1	
2	PCI_2 Output enable	0 = Disabled, 1 = Enabled	RW	1	
1	PCI_1 Output enable	0 = Disabled, 1 = Enabled	RW	1	
0	PCI_0 Output enable	0 = Disabled, 1 = Enabled	RW	1	

**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte4 Control Register

Bit	Description	Contents	Type	Default	Note
7	USB_48 2x output drive	0 = 2x Drive strength, 1 = Normal	RW	0	
6	USB_48MHz Output Enable	0 = Disabled, 1 = Enabled	RW	1	
5	Allow control of PCIF_2 with assertion of PCI_STOP#	0 = Free Running 1 = Stopped with PCI_STOP#	RW	0	
4	Allow control of PCIF_1 with assertion of PCI_STOP#	0 = Free Running 1 = Stopped with PCI_STOP#	RW	0	
3	Allow control of PCIF_0 with assertion of PCI_STOP#	0 = Free Running 1 = Stopped with PCI_STOP#	RW	0	
2	PCIF_2 Output enable	0 = Disabled, 1 = Enabled	RW	1	
1	PCIF_1 Output enable	0 = Disabled, 1 = Enabled	RW	1	
0	PCIF_0 Output enable	0 = Disabled, 1 = Enabled	RW	1	

Byte5 Control Register

Bit	Description	Contents	Type	Default	Note
7	DOT_48MHz Output Enable	0 = Disabled, 1 = Enabled	RW	1	
6	Reserved		RW	1	
5	VCH Select 66MHz / 48MHz	0 = 3V66 mode 1 = VCH (48 MHz) mode	RW	0	
4	3V66_4/VCH Output Enable	0 = Disabled (tristate), 1 = Enabled	RW	1	
3	3V66_3 Output Enable	0 = Disabled, 1 = Enabled	RW	1	
2	3V66_2 Output Enable	0 = Disabled, 1 = Enabled	RW	1	
1	3V66_1 Output Enable	0 = Disabled, 1 = Enabled	RW	1	
0	3V66_0 Output Enable	0 = Disabled, 1 = Enabled	RW	1	

Byte6 Control Register

Bit	Description	Contents	Type	Default	Note
7	Test Clock Mode	0 = Disabled, 1 = Enabled	RW	0	
6	Reserved		RW	0	
5	FS_A & FS_B Operation	0 = Normal, 1 = Test mode	RW	0	
4	SRC Frequency Select	0 = 100MHz, 1 = 200 MHz	RW	0	
3	Reserved		RW	0	
2	Spread Spectrum Mode	0 = Spread OFF 1 = Spread ON	RW	0	See B9[7:6]
1	REF1 Output Enable	0 = Disabled, 1 = Enabled	RW	1	
0	REF0 Output Enable	0 = Disabled, 1 = Enabled	RW	1	

## I<sup>2</sup>C Controlled Register Bit Map (cont.)

### Byte7 Vendor Identification Register

Bit	Description	Contents	Type	Default	Note
7	Revision Code Bit3	Vendor Specific	R	0	
6	Revision Code Bit2	Vendor Specific	R	0	
5	Revision Code Bit1	Vendor Specific	R	0	
4	Revision Code Bit0	Vendor Specific	R	1	
3	Vendor ID Bit3	Vendor Specific	R	1	
2	Vendor ID Bit2	Vendor Specific	R	1	
1	Vendor ID Bit1	Vendor Specific	R	1	
0	Vendor ID Bit0	Vendor Specific	R	1	

### Byte8 Read Back Byte Count Register

Bit	Description	Contents	Type	Default	Note
7	Read back byte count Bit7	Writing to this register will configure byte Count and how many bytes will be read back. Default is 1Ehex = 30 bytes.	RW	0	
6	Read back byte count Bit6		RW	0	
5	Read back byte count Bit5		RW	0	
4	Read back byte count Bit4		RW	1	
3	Read back byte count Bit3		RW	1	
2	Read back byte count Bit2		RW	1	
1	Read back byte count Bit1		RW	1	
0	Read back byte count Bit0		RW	0	

**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte9 Control Register

Bit	Description	Contents	Type	Default	Note
7	SSC2 Enable Bit	B6[2] = 0 or B9[7] = 1 : SSC2 = OFF B6[2] = 1 & B9[7] = 0 : SSC2 = ON	RW	0	
6	SSC1 Enable Bit	B6[2] = 0 or B9[6] = 1 : SSC1 = OFF B6[2] = 1 & B9[6] = 0 : SSC1 = ON	RW	0	
5	Clock Frequency Control Bit4	Latched input PCIF_1 at Power ON	RW	X	See Table 6
4	Clock Frequency Control Bit3	Latched input DOT48 at Power ON	RW	X	
3	Clock Frequency Control Bit2	Latched input PCIF_0 at Power ON	RW	X	
2	Clock Frequency Control Bit1	Latched input FS_A at Power ON	RW	X	
1	Clock Frequency Control Bit0	Latched input FS_B at Power ON	RW	X	
0	Frequency Select Mode Bit	0 = Freq. is selected by latched input FS_A and FS_B 1 = Freq. is selected by I <sup>2</sup> C B9[5:1]	RW	0	

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I<sup>2</sup>C Controlled Register Bit Map (cont.)

Table6 Clock Frequency Function Table

No.	FS_4	FS_3	FS_2	FS_A	FS_B	CPU [MHz]	SRC [MHz]	3V66 [MHz]	PCI [MHz]
	B9[5]	B9[4]	B9[3]	B9[2]	B9[1]				
0	0	0	0	0	0	100.02	100.02	66.68	33.34
1	0	0	0	0	1	200.03	100.02	66.68	33.34
2	0	0	0	1	0	133.36	100.02	66.68	33.34
3	0	0	0	1	1	166.69	100.02	66.68	33.34
4	0	0	1	0	0	200.03	100.02	66.68	33.34
5	0	0	1	0	1	400.07	100.02	66.68	33.34
6	0	0	1	1	0	266.71	100.02	66.68	33.34
7	0	0	1	1	1	333.39	100.02	66.68	33.34
8	0	1	0	0	0	138.69	100.02	66.68	33.34
9	0	1	0	0	1	142.25	100.02	66.68	33.34
10	0	1	0	1	0	145.80	100.02	66.68	33.34
11	0	1	0	1	1	149.36	100.02	66.68	33.34
12	0	1	1	0	0	152.91	100.02	66.68	33.34
13	0	1	1	0	1	156.47	100.02	66.68	33.34
14	0	1	1	1	0	160.03	100.02	66.68	33.34
15	0	1	1	1	1	163.58	100.02	66.68	33.34
16	1	0	0	0	0	167.14	100.02	66.68	33.34
17	1	0	0	0	1	170.70	100.02	66.68	33.34
18	1	0	0	1	0	174.25	100.02	66.68	33.34
19	1	0	0	1	1	177.81	100.02	66.68	33.34
20	1	0	1	0	0	181.36	100.02	66.68	33.34
21	1	0	1	0	1	184.92	100.02	66.68	33.34
22	1	0	1	1	0	186.70	100.02	66.68	33.34
23	1	0	1	1	1	189.36	100.02	66.68	33.34
24	1	1	0	0	0	192.03	100.02	66.68	33.34
25	1	1	0	0	1	194.70	100.02	66.68	33.34
26	1	1	0	1	0	197.37	100.02	66.68	33.34
27	1	1	0	1	1	200.03	100.02	66.68	33.34
28	1	1	1	0	0	202.70	100.02	66.68	33.34
29	1	1	1	0	1	205.37	100.02	66.68	33.34
30	1	1	1	1	0	208.03	100.02	66.68	33.34
31	1	1	1	1	1	210.70	100.02	66.68	33.34

**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte10 Control Register

Bit	Description	Contents	Type	Default	Note
7	SSC Spread Select Bit[2:0]	Bit[2:0] =	RW	0	
6		000 = -0.500%, 100 = ±0.250%	RW	0	
5		001 = -0.750%, 101 = ±0.375%	RW	0	
		010 = -1.000%, 110 = ±0.500%			
		011 = -1.500%, 111 = ±0.750%			
4	Backup of latch Input FS_4 at Power ON	When SAFE_F# is Enable (B15[5]=1)	R	X	
3	Backup of latch Input FS_3 at Power ON	PWRDWN#/SAFE_F# pin to "Low", and if B23[1]=0, frequency selection is changed to these	R	X	
2	Backup of latch Input FS_2 at Power ON	setting and PWRDWN#/SAFE_F# pin to	R	X	
1	Backup of latch Input FS_A at Power ON	"High", frequency selection is changed back to the last mode.	R	X	
0	Backup of latch Input FS_B at Power ON		R	X	

Byte11 Control Register

Bit	Description	Contents	Type	Default	Note
7	PCI_STOP# Enable Control Bit	0 = Enable , 1 = Disable	RW	0	
6	CPU_STOP# Enable Control Bit	0 = Enable , 1 = Disable	RW	0	
5	PWRDWN# Enable Control Bit	0 = Enable , 1 = Disable	RW	0	
4	Backup of B9[5] written by I <sup>2</sup> C	When SAFE_F# is Enable (B15[5]=1)	R	X	
3	Backup of B9[4] written by I <sup>2</sup> C	PWRDWN#/SAFE_F# pin to	R	X	
2	Backup of B9[3] written by I <sup>2</sup> C	"Low", and if B23[1]=1, frequency selection is changed to	R	X	
1	Backup of B9[2] written by I <sup>2</sup> C	these setting and	R	X	
0	Backup of B9[1] written by I <sup>2</sup> C	PWRDWN#/SAFE_F# pin to "High", frequency selection is changed back to the last mode.	R	X	



**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte12 Control Register

Bit	Description	Contents	Type	Default	Note
7	Reserved		R/W	0	
6	Reserved		R/W	0	
5	Reserved		R/W	0	
4	Reserved		R/W	0	
3	Reserved		R/W	0	
2	PLL1 Output (VCO1) Frequency Control Bit (M1/N1 Divider Control Bit) PLL1 : for SRC/3V66/PCI_PLL	0 = Normal mode PLL1 M1[6:0] and N1[9:0] are changed on Table 5 selection decided by FS4/3/2/A/B or B9[5:1] 1 = Over or Down clocking mode PLL1 M1[6:0] and N1[9:0] are changed by B12[1:0], B13[7:0] and B14[6:0]. B12[1:0], B13[7:0] and B14[6:0] are able to be changed at B12[2] = 1.	R/W	0	See Note 1
1	PLL1 N1 Divider Control Bit9	N1[9]	R/W	0	
0	PLL1 N1 Divider Control Bit8	N1[8]	R/W	0	

Note: 1. B12[1:0], B13[7:0] and B14[6:0] must be written together (at writing B14) in every case.

Byte13 Control Register

Bit	Description	Contents	Type	Default	Note
7	PLL1 N1 Divider Control Bit7	N1[7]	R/W	0	See Note 1
6	PLL1 N1 Divider Control Bit6	N1[6]	R/W	1	
5	PLL1 N1 Divider Control Bit5	N1[5]	R/W	0	
4	PLL1 N1 Divider Control Bit4	N1[4]	R/W	0	
3	PLL1 N1 Divider Control Bit3	N1[3]	R/W	1	
2	PLL1 N1 Divider Control Bit2	N1[2]	R/W	0	
1	PLL1 N1 Divider Control Bit1	N1[1]	R/W	1	
0	PLL1 N1 Divider Control Bit0	N1[0]	R/W	1	

Note: 1. B12[1:0], B13[7:0] and B14[6:0] must be written together (at writing B14) in every case.

**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte14 Control Register

Bit	Description	Contents	Type	Default	Note
7	Reserved		R/W	0	See Note 1
6	PLL1 M1 Divider Control Bit6	M1[6]	R/W	0	
5	PLL1 M1 Divider Control Bit5	M1[5]	R/W	0	
4	PLL1 M1 Divider Control Bit4	M1[4]	R/W	1	
3	PLL1 M1 Divider Control Bit3	M1[3]	R/W	0	
2	PLL1 M1 Divider Control Bit2	M1[2]	R/W	0	
1	PLL1 M1 Divider Control Bit1	M1[1]	R/W	1	
0	PLL1 M1 Divider Control Bit0	M1[0]	R/W	0	

Note: 1. B12[1:0], B13[7:0] and B14[6:0] must be written together (at writing B14) in every case.

Byte15 Control Register

Bit	Description	Contents	Type	Default	Note
7	PCI_5 Output Frequency Select Bit	0 = 33.3 MHz, 1 = 25 MHz	R/W	0	
6	USB_48 Output Frequency Select Bit	0 = 48MHz, 1 = 24 MHz	R/W	0	
5	SAFE_F# Input mode select Bit	0 = PWRDWN# input mode 1 = SAFE_F# input mode Default is PWRDWN# input. SAFE_F# is active "Low" input. When SAFE_F# is "Low", frequency mode is changed to the predefined frequency mode. Predefined frequency mode is selected by B23[1].	R/W	0	
4	Clock Divider Control Bit	0 = Normal mode Clock dividers are changed by Table 5 selection decided B9[5:1] 1 = Over or Down clocking mode Clock dividers are changed by B15[3:0] and B16[7:0]. B15[3:0] and B16[7:0] are able to be changed at B15[4] = 1.	R/W	0	
3	CPU Divider Control Bit3	0001 = 1/1,      0111 = 1/7	R/W	X	
2	CPU Divider Control Bit2	0010 = 1/2,      1000 = 1/8 0011 = 1/3,      1001 = 1/9	R/W	X	
1	CPU Divider Control Bit1	0100 = 1/4,      1010 = 1/10	R/W	X	
0	CPU Divider Control Bit0	0101 = 1/5,      1011 = 1/11 0110 = 1/6,	R/W	X	

**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte16 Control Register

Bit	Description	Contents	Type	Default	Note
7	3V66 / PCI / PCIF Divider Control Bit3	3V66 divider ratio = 0010 = 1/2,      0111 = 1/7 0011 = 1/3,      1000 = 1/8	R/W	X	
6	3V66 / PCI / PCIF Divider Control Bit2	0100 = 1/4,      1001 = 1/9 0101 = 1/5,      1010 = 1/10 0110 = 1/6,      1011 = 1/11	R/W	X	
5	3V66 / PCI / PCIF Divider Control Bit1	PCI / PCIF divider ratio = 3v66 x 1/2	R/W	X	
4	3V66 / PCI / PCIF Divider Control Bit0		R/W	X	
3	SRC Divider Control Bit3	0001 = 1/1,      0111 = 1/7 0010 = 1/2,      1000 = 1/8	R/W	X	
2	SRC Divider Control Bit2	0011 = 1/3,      1001 = 1/9	R/W	X	
1	SRC Divider Control Bit1	0100 = 1/4,      1010 = 1/10	R/W	X	
0	SRC Divider Control Bit0	0101 = 1/5,      1011 = 1/11 0110 = 1/6	R/W	X	

Byte17 Control Register

Bit	Description	Contents	Type	Default	Note
7	Reserved		R/W	0	
6	Reserved		R/W	0	
5	Reserved		R/W	0	
4	PLL2 Output (VCO2) Frequency Control Bit (M2 / N2 Divider Control Bit) PLL2 : for CPU	0 = Normal mode VCO2 frequency is changed on Table 5 selection decided by FS4/3/2/A/B or B9[5:1]. 1 = Over or Down clocking mode VCO2 frequency is changed by B17[3:0] and B18[7:0] with decimal. B17[3:0] and B18[7:0] are able to be changed at B17[4] = 1.	R/W	0	See Note 1
3	VCO2 Frequency Control Bit11	These bits are 100MHz digit of VCO2 frequency.	R/W	0	
2	VCO2 Frequency Control Bit10	0000 = 0, 0001 = 1 .... 1001 = 9	R/W	1	
1	VCO2 Frequency Control Bit9		R/W	0	
0	VCO2 Frequency Control Bit8		R/W	0	

Note: 1. B17[3:0] and B18[7:0] must be written together (at writing B18) in every case.

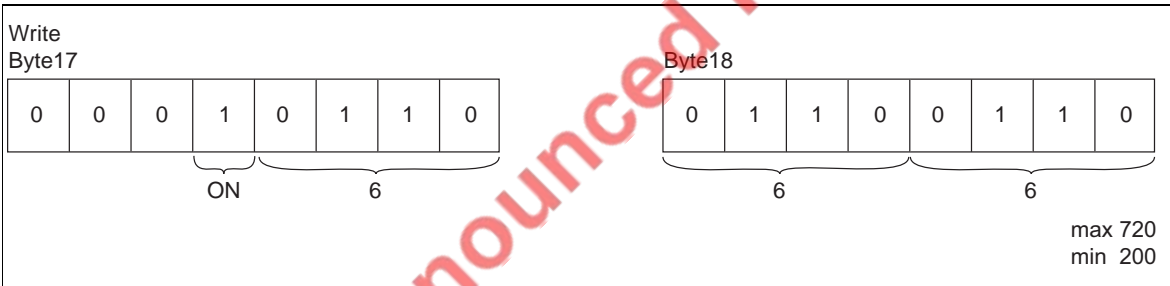
**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte18 Control Register

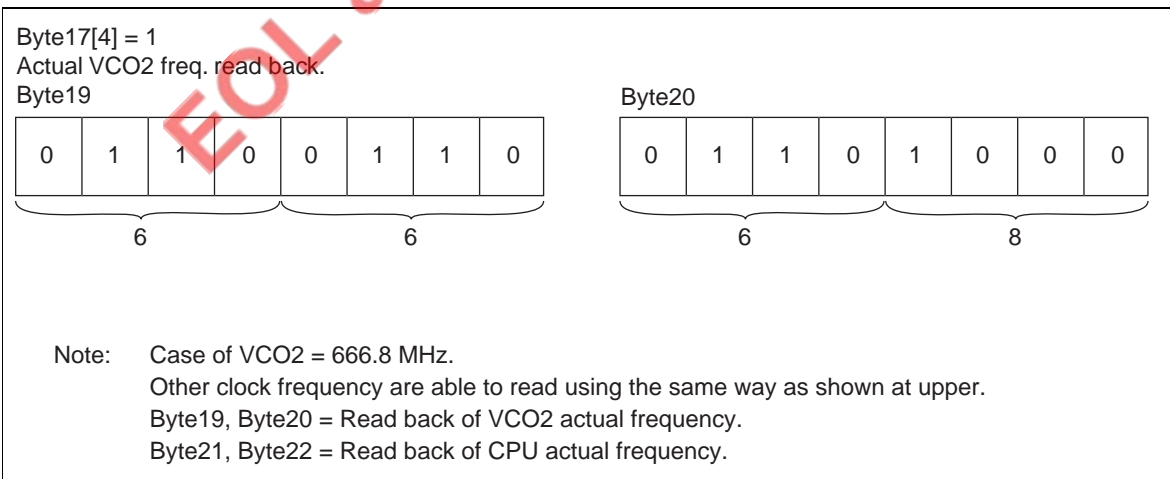
Bit	Description	Contents	Type	Default	Note
7	VCO2 Frequency Control Bit7	These bits are 10MHz digit of VCO2 frequency. 0000 = 0, 0001 = 1 .... 1001 = 9	R/W	0	See Note 1
6	VCO2 Frequency Control Bit6		R/W	0	
5	VCO2 Frequency Control Bit5		R/W	0	
4	VCO2 Frequency Control Bit4		R/W	0	
3	VCO2 Frequency Control Bit3	These bits are 1MHz digit of VCO2 frequency. 0000 = 0, 0001 = 1 .... 1001 = 9	R/W	0	
2	VCO2 Frequency Control Bit2		R/W	0	
1	VCO2 Frequency Control Bit1		R/W	0	
0	VCO2 Frequency Control Bit0		R/W	0	

Note: 1. B17[3:0] and B18[7:0] must be written together (at writing B18) in every case.

How to set VCO2 frequency to 666 MHz.



How to read actual frequency of VCO2 and CPU clock



**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte19 Control Register

Bit	Description	Contents	Type	Default	Note
7	VCO2 Frequency Read Bit15	Calculation result of VCO2	R	0	
6	VCO2 Frequency Read Bit14	frequency.	R	0	
5	VCO2 Frequency Read Bit13	100 MHz digit	R	0	
4	VCO2 Frequency Read Bit12	0000 = 0, 0001 = 1 .... 1001 = 9	R	0	
3	VCO2 Frequency Read Bit11	Calculation result of VCO2	R	0	
2	VCO2 Frequency Read Bit10	frequency.	R	0	
1	VCO2 Frequency Read Bit9	10 MHz digit	R	0	
0	VCO2 Frequency Read Bit8	0000 = 0, 0001 = 1 .... 1001 = 9	R	0	

Byte20 Control Register

Bit	Description	Contents	Type	Default	Note
7	VCO2 Frequency Read Bit7	Calculation result of VCO2	R	0	
6	VCO2 Frequency Read Bit6	frequency.	R	0	
5	VCO2 Frequency Read Bit5	1 MHz digit	R	0	
4	VCO2 Frequency Read Bit4	0000 = 0, 0001 = 1 .... 1001 = 9	R	0	
3	VCO2 Frequency Read Bit3	Calculation result of VCO2	R	0	
2	VCO2 Frequency Read Bit2	frequency.	R	0	
1	VCO2 Frequency Read Bit1	0.1 MHz digit	R	0	
0	VCO2 Frequency Read Bit0	0000 = 0, 0001 = 1 .... 1001 = 9	R	0	

Byte21 Control Register

Bit	Description	Contents	Type	Default	Note
7	CPU Frequency Read Bit15	Calculation result of CPU	R	0	
6	CPU Frequency Read Bit14	frequency.	R	0	
5	CPU Frequency Read Bit13	100 MHz digit	R	0	
4	CPU Frequency Read Bit12	0000 = 0, 0001 = 1 .... 1001 = 9	R	0	
3	CPU Frequency Read Bit11	Calculation result of CPU	R	0	
2	CPU Frequency Read Bit10	frequency.	R	0	
1	CPU Frequency Read Bit9	10 MHz digit	R	0	
0	CPU Frequency Read Bit8	0000 = 0, 0001 = 1 .... 1001 = 9	R	0	

**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte22 Control Register

Bit	Description	Contents	Type	Default	Note
7	CPU Frequency Read Bit7	Calculation result of CPU frequency.	R	0	
6	CPU Frequency Read Bit6	1 MHz digit	R	0	
5	CPU Frequency Read Bit5	0000 = 0, 0001 = 1 .... 1001 = 9	R	0	
4	CPU Frequency Read Bit4		R	0	
3	CPU Frequency Read Bit3	Calculation result of CPU frequency.	R	0	
2	CPU Frequency Read Bit2	0.1 MHz digit	R	0	
1	CPU Frequency Read Bit1	0000 = 0, 0001 = 1 .... 1001 = 9	R	0	
0	CPU Frequency Read Bit0		R	0	

Byte23 Control Register

Bit	Description	Contents	Type	Default	Note
7	Watchdog Enable Control Bit	0 = Disable , Pin22 = 3V66_0 output 1 = Enable , Pin22 = RESET# output	R/W	0	
6	RESET# Reverse Control Bit	0 = Normal , 1 = Reverse	R/W	0	
5	Watchdog Timer Count Bit3	These 4 bits corresponds to how many watchdog timer will wait from becoming "Alarm mode" (B23[0] = 1) to outputting RESET# pin to "Low". Default is 586ms x8 = 4.7s at Power ON	R/W	1	
4	Watchdog Timer Count Bit2		R/W	0	
3	Watchdog Timer Count Bit1		R/W	0	
2	Watchdog Timer Count Bit0		R/W	0	
1	Backup Frequency Select Bit	0 = B10[4:0] , 1 = B11[4:0] When SAFE_F# is "Low" , frequency mode is changed to the predefined frequency mode decided by B10[4:0] or B11[4:0].	R/W	0	
0	Watchdog Status Bit	0 = Normal mode, 1 = Alarm mode	R/W	0	

**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte24 Control Register

Bit	Description	Contents	Type	Default	Note
7	Reserved		R/W	0	
6	PCI_STOP# Stop PCI_6 Control Bit	0 = Stoppable, 1 = Free running	R/W	0	
5	PCI_STOP# Stop PCI_5 Control Bit	0 = Stoppable, 1 = Free running	R/W	0	
4	PCI_STOP# Stop PCI_4 Control Bit	0 = Stoppable, 1 = Free running	R/W	0	
3	PCI_STOP# Stop PCI_3 Control Bit	0 = Stoppable, 1 = Free running	R/W	0	
2	PCI_STOP# Stop PCI_2 Control Bit	0 = Stoppable, 1 = Free running	R/W	0	
1	PCI_STOP# Stop PCI_1 Control Bit	0 = Stoppable, 1 = Free running	R/W	0	
0	PCI_STOP# Stop PCI_0 Control Bit	0 = Stoppable, 1 = Free running	R/W	0	

Byte25 Control Register

Bit	Description	Contents	Type	Default	Note
7	CPU Clock Skew1 Control Bit3	Delay Ahead 1000 = +0.00ns, 0111 = -0.20ns	R/W	1	See Note 1
6	CPU Clock Skew1 Control Bit2	1001 = +0.20ns, 0110 = -0.40ns 1010 = +0.40ns, 0101 = -0.60ns 1011 = +0.60ns, 0100 = -0.80ns	R/W	0	
5	CPU Clock Skew1 Control Bit1	1100 = +0.80ns, 0011 = -1.00ns 1101 = +1.00ns, 0010 = -1.20ns	R/W	0	
4	CPU Clock Skew1 Control Bit0	1110 = +1.20ns, 0001 = -1.40ns 1111 = +1.40ns, 0000 = -1.60ns	R/W	0	
3	CPU Clock Skew2 Control Bit3	Delay Ahead 1000 = +0.00ns, 0111 = -0.15ns	R/W	1	See Note 1
2	CPU Clock Skew2 Control Bit2	1001 = +0.15ns, 0110 = -0.30ns 1010 = +0.30ns, 0101 = -0.45ns 1011 = +0.45ns, 0100 = -0.60ns	R/W	0	
1	CPU Clock Skew2 Control Bit1	1100 = +0.60ns, 0011 = -0.75ns 1101 = +0.75ns, 0010 = -0.90ns	R/W	0	
0	CPU Clock Skew2 Control Bit0	1110 = +0.90ns, 0001 = -1.05ns 1111 = +1.05ns, 0000 = -1.20ns	R/W	0	

Note: 1. Total CPU Clock Skew is Skew1+Skew2.

**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte26 Control Register

Bit	Description	Contents	Type	Default	Note
7	PCIF / PCI Clock Skew2 Control Bit3	Skew2 is "Late" Skew that is Delay Time from "Normal" Skew1.	R/W	0	See Note 1
6	PCIF / PCI Clock Skew2 Control Bit2	0000 = +0.0ns, 1000 = +3.2ns 0001 = +0.4ns, 1001 = +3.6ns 0010 = +0.8ns, 1010 = +4.0ns	R/W	0	
5	PCIF / PCI Clock Skew2 Control Bit1	0011 = +1.2ns, 1011 = +4.4ns 0100 = +1.6ns, 1100 = +4.8ns	R/W	0	
4	PCIF / PCI Clock Skew2 Control Bit0	0101 = +2.0ns, 1101 = +5.2ns 0110 = +2.4ns, 1110 = +5.6ns 0111 = +2.8ns, 1111 = +6.0ns	R/W	0	
3	PCIF / PCI Clock Skew1 Control Bit3	Skew1 is "Normal" Skew. Delay Ahead	R/W	1	See Note 1
2	PCIF / PCI Clock Skew1 Control Bit2	1000 = +0.0ns, 0111 = -0.4ns 1001 = +0.4ns, 0110 = -0.8ns 1010 = +0.8ns, 0101 = -1.2ns	R/W	0	
1	PCIF / PCI Clock Skew1 Control Bit1	1011 = +1.2ns, 0100 = -1.6ns 1100 = +1.6ns, 0011 = -2.0ns	R/W	0	
0	PCIF / PCI Clock Skew1 Control Bit0	1101 = +2.0ns, 0010 = -2.4ns 1110 = +2.4ns, 0001 = -2.8ns 1111 = +2.8ns, 0000 = -3.2ns	R/W	0	

Note: 1. PCIF / PCI Clock Skew is Skew1 (= Normal) or Skew1+Skew2 (= Late).

Byte27 Control Register

Bit	Description	Contents	Type	Default	Note
7	Reserved		R/W	0	
6	PCIF_2 Skew Select Bit	0 = Normal, 1 = Late	R/W	0	See Note 1
5	PCIF_1 Skew Select Bit	0 = Normal, 1 = Late	R/W	0	
4	PCIF_0 Skew Select Bit	0 = Normal, 1 = Late	R/W	0	
3	3V66 Clock Skew Control Bit3	Delay Ahead 1000 = +0.0ns, 0111 = -0.4ns 1001 = +0.4ns, 0110 = -0.8ns	R/W	1	
2	3V66 Clock Skew Control Bit2	1010 = +0.8ns, 0101 = -1.2ns 1011 = +1.2ns, 0100 = -1.6ns	R/W	0	
1	3V66 Clock Skew Control Bit1	1100 = +1.6ns, 0011 = -2.0ns 1101 = +2.0ns, 0010 = -2.4ns	R/W	0	
0	3V66 Clock Skew Control Bit0	1110 = +2.4ns, 0001 = -2.8ns 1111 = +2.8ns, 0000 = -3.2ns	R/W	0	

Note: 1. Normal = Skew1(B26[3:0]), Late = Skew1(B26[3:0]) +Skew2 (B26[7:4]).



**I<sup>2</sup>C Controlled Register Bit Map (cont.)**

Byte28 Control Register

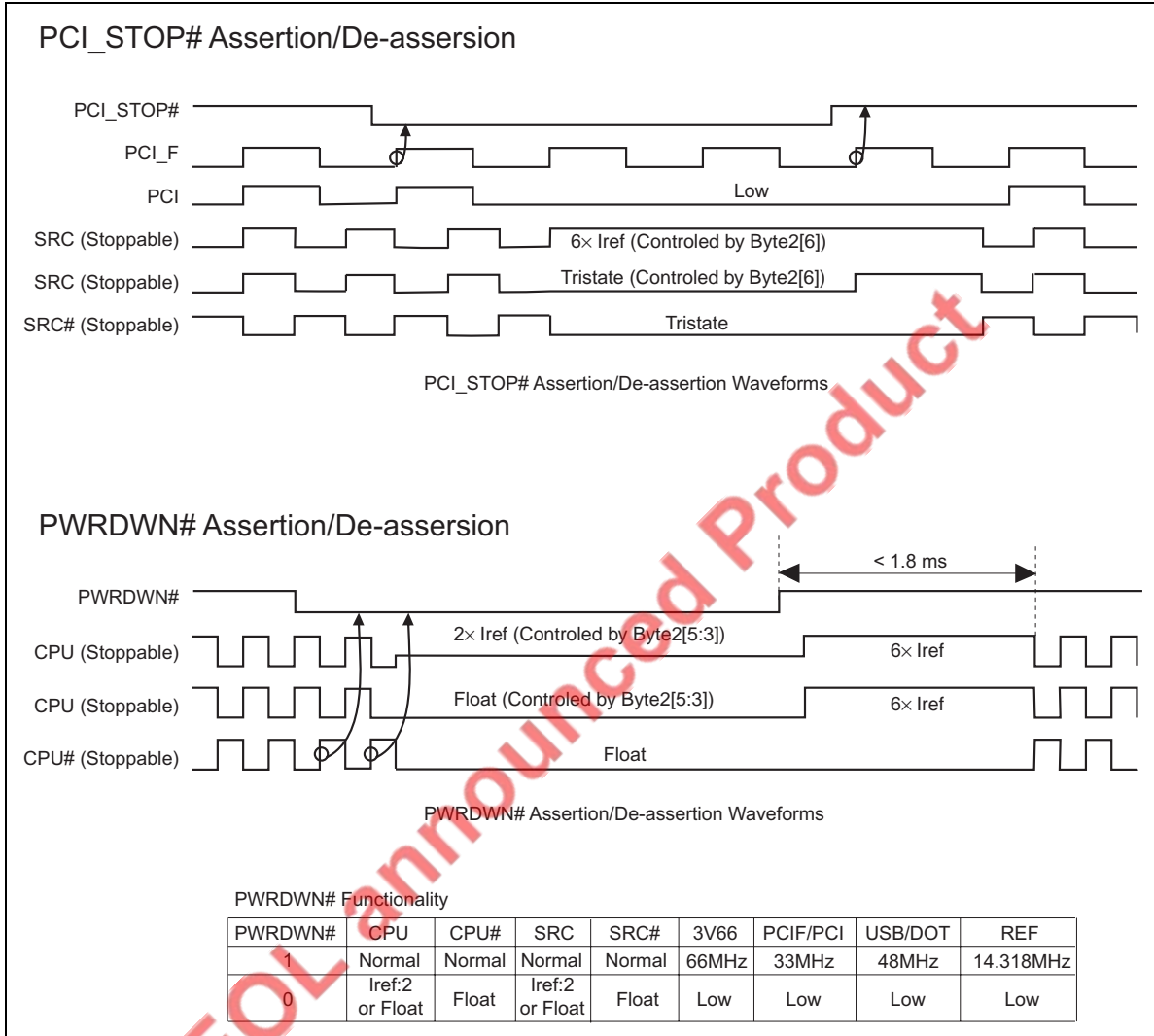
Bit	Description	Contents	Type	Default	Note
7	Reserved	0 = Normal, 1 = Late	R/W	0	
6	PCI_6 Skew Select Bit	0 = Normal, 1 = Late	R/W	0	See Note 1
5	PCI_5 Skew Select Bit	0 = Normal, 1 = Late	R/W	0	
4	PCI_4 Skew Select Bit	0 = Normal, 1 = Late	R/W	0	
3	PCI_3 Skew Select Bit	0 = Normal, 1 = Late	R/W	0	
2	PCI_2 Skew Select Bit	0 = Normal, 1 = Late	R/W	0	
1	PCI_1 Skew Select Bit	0 = Normal, 1 = Late	R/W	0	
0	PCI_0 Skew Select Bit	0 = Normal, 1 = Late	R/W	0	

Note: 1. Normal = Skew1(B26[3:0]), Late = Skew1(B26[3:0]) +Skew2 (B26[7:4]).

Byte29 Control Register

Bit	Description	Contents	Type	Default	Note
7	VCH Slew Rate Control Bit1	00 = Normal, 10 = “++”	R/W	1	
6	VCH Slew Rate Control Bit0	01 = “+” , 11 = “-”	R/W	0	
5	PCI Slew Rate Control Bit1	00 = Normal, 10 = “++”	R/W	1	
4	PCI Slew Rate Control Bit0	01 = “+” , 11 = “-”	R/W	0	
3	PCIF Slew Rate Control Bit1	00 = Normal, 10 = “++”	R/W	1	
2	PCIF Slew Rate Control Bit0	01 = “+” , 11 = “-”	R/W	0	
1	3V66 Slew Rate Control Bit1	00 = Normal, 10 = “++”	R/W	1	
0	3V66 Slew Rate Control Bit0	01 = “+” , 11 = “-”	R/W	0	

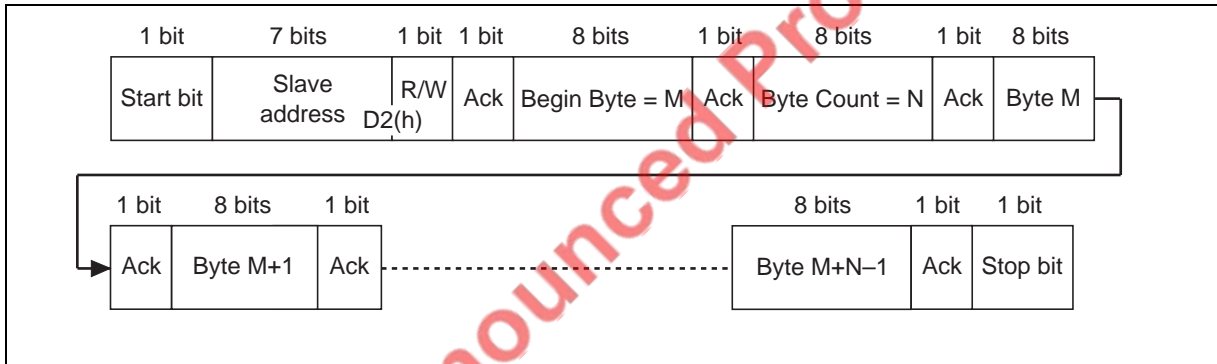
**Clock Stop Timing Diagram**



## Renesas clock generator I<sup>2</sup>C Serial Interface Operation

### 1. Write mode

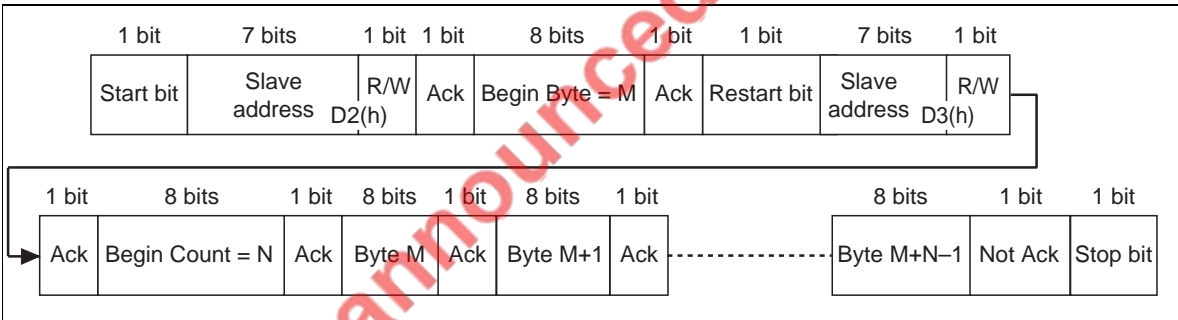
- 1.1 Controller (host) sends a start bit.
- 1.2 Controller (host) sends the write address D2 (h).
- 1.3 Renesas clock generator will acknowledge (Renesas clock gen. sends “Low”).
- 1.4 Controller (host) sends a begin byte M.
- 1.5 Renesas clock generator will acknowledge (Renesas clock gen. sends “Low”).
- 1.6 Controller (host) sends a byte count N.
- 1.7 Renesas clock generator will acknowledge (Renesas clock gen. sends “Low”).
- 1.8 Controller (host) sends data from byte M to byte M+N-1.
- 1.9 Renesas clock generator will acknowledge each byte one at a time.
- 1.10 Controller (host) sends a stop bit.



**Renesas clock generator I<sup>2</sup>C Serial Interface Operation (cont.)**

**2. Read mode**

- 2.1 Controller (host) sends a start bit.
- 2.2 Controller (host) sends the write address D2 (h).
- 2.3 Renesas clock generator will acknowledge (Renesas clock gen. sends “Low”).
- 2.4 Controller (host) sends a begin byte M.
- 2.5 Renesas clock generator will acknowledge (Renesas clock gen. sends “Low”).
- 2.6 Controller (host) sends a restart bit.
- 2.7 Controller (host) sends the read address D3 (h).
- 2.8 Renesas clock generator will acknowledge (Renesas clock gen. sends “Low”).
- 2.9 Renesas clock generator will send the byte count N.
- 2.10 Controller (host) will acknowledge.
- 2.11 Renesas clock generator will send data from byte M to byte M+N-1.
- 2.12 When Renesas clock generator sends the last byte, controller (host) will not acknowledge.
- 2.13 Controller (host) sends a stop bit.



- Notes:
- 1. Renesas clock generator is a slave/receiver, I<sup>2</sup>C component. It can read back the data stored in the latches for the verification.
  - 2. The data transfer rate supported by this clock generator is 100k bits/sec or less (standard mode).
  - 3. The input is operating at 3.3 V logic levels.
  - 4. The data byte format is 8 bit bytes.
  - 5. To simplify the clock generator I<sup>2</sup>C interface, the protocol is set to use only block-write from the controller.
  - 6. The bytes must be accessed in sequential order from lowest to highest byte with the ability to stop after any complete byte has been transferred. The data is loaded until a stop sequence is issued.
  - 7. At power-on, all registers are set to a default condition, as shown.

**Absolute Maximum Ratings**

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	VDD	-0.5 to 4.6	V	
Input voltage	V <sub>I</sub>	-0.5 to 4.6	V	
Output voltage *1	V <sub>O</sub>	-0.5 to VDD +0.5	V	
Input clamp current	I <sub>IK</sub>	-50	mA	V <sub>I</sub> < 0
Output clamp current	I <sub>OK</sub>	-50	mA	V <sub>O</sub> < 0
Continuous output current	I <sub>O</sub>	±50	mA	V <sub>O</sub> = 0 to VDD
Maximum power dissipation at T <sub>a</sub> = 55°C (in still air)		0.7	W	
Storage temperature	T <sub>stg</sub>	-65 to +150	°C	

Notes: Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

1. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

**Recommended Operating Conditions**

Item	Symbol	Min	Typ	Max	Unit	Conditions
Supply voltage	VDD	3.135	3.3	3.465	V	
Supply voltage	VDDA	3.135	3.3	3.465	V	
DC input signal voltage		-0.3	—	VDD+0.3	V	
High level input voltage	V <sub>IH</sub>	2.0	—	VDD+0.3	V	
Low level input voltage	V <sub>IL</sub>	-0.3	—	0.8	V	
Operating temperature	T <sub>a</sub>	0	—	70	°C	

**DC Electrical Characteristics / Serial Input Port**

Ta = 0°C to 70°C, VDD = 3.3 V

Item	Symbol	Min	Typ *1	Max	Unit	Test Conditions
Input Low Voltage	V <sub>IL</sub>	—	—	0.8	V	
Input High Voltage	V <sub>IH</sub>	2.0	—	—	V	
Input Current	I <sub>I</sub>	-50	—	+50	μA	VI = 0 V or 3.465 V, VDD = 3.465 V
Input capacitance	C <sub>I</sub>	—	10	—	pF	SDATA & SCLK

Note: 1. For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditions.

**AC Electrical Characteristics / Serial Input port**

Ta = 0°C to 70°C, VDD = 3.3 V

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	Notes
SCLK Frequency	F <sub>SCLK</sub>	—	—	100	kHz	Normal Mode	
Start Hold Time	t <sub>STHD</sub>	4.0	—	—	μs		
SCLK Low Time	t <sub>LOW</sub>	4.7	—	—	μs		
SCLK High Time	t <sub>HIGH</sub>	4.0	—	—	μs		
Data Setup Time	t <sub>DSU</sub>	250	—	—	ns		
Data Hold Time	t <sub>DHD</sub>	300	—	—	ns		
Stop Setup Time	t <sub>STSU</sub>	4.0	—	—	μs		
BUS Free Time between Stop & Start Condition	t <sub>SPF</sub>	4.7	—	—	μs		

**DC Electrical Characteristics CPU/CPU# Clock**

Ta = 0°C to 70°C, VDD = 3.3 V, Iref = 475 Ω

Item	Symbol	Min	Typ *1	Max	Unit	Test Conditions
Output voltage	V <sub>O</sub>	—	—	1.20	V	R <sub>p</sub> = 49.9 Ω, VDD = 3.3 V
Output Current	I <sub>o</sub>	—	I(nom) *2	—	mA	VDD = 3.3 V
Output resistance		3000	—	—	Ω	V <sub>O</sub> = 1.2 V

- Notes: 1. For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditional (nom) is output current(Ioh) shown in below.  
 2. Ioh = VDD/(3Rr) = 3.3/(3x475) = 2.32 mA,  
 Ioh x6 = 13.89 mA (Voh @Z: 0.695 V @50 Ω),  
 Ioh x2 = 4.63 mA (Voh @Z: 0.232 V @50 Ω)

**AC Electrical Characteristics CPU/CPU# Clock (CPU at 0.7V Timing)**

Ta = 0°C to 70°C, VDD = 3.3 V, C<sub>L</sub> = 2 pF, R<sub>s</sub> = 33.2 Ω, R<sub>p</sub> = 49.9 Ω

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	Notes
Cycle to cycle jitter	t <sub>ccs</sub>	—	125	—	ps		Note1
CPU Group Skew (CPU clock out to CPU clock out)	t <sub>skS</sub>	—	100	—	ps		
Rise time	t <sub>r</sub>	175	—	700	ps	V <sub>O</sub> = 0.175 V to 0.525 V	200MHz
Fall time	t <sub>f</sub>	175	—	700	ps	V <sub>O</sub> = 0.175 V to 0.525 V	200MHz
Clock Duty Cycle		45	50	55	%		200MHz
CPU clock period(100)		—	9.99	—	ns		
CPU clock period(133)		—	7.49	—	ns		
CPU clock period(166)		—	5.99	—	ns		
CPU clock period(200)		—	4.99	—	ns		
Cross point(0.7V) voltage	V <sub>cross</sub>	0.25	—	0.55	V		200MHz

Note: 1. Difference of cycle time between two adjoining cycles.

**DC Electrical Characteristics SRC/SRC# Clock**

Ta = 0°C to 70°C, VDD = 3.3 V, Iref = 475 Ω

Item	Symbol	Min	Typ *1	Max	Unit	Test Conditions
Output voltage	VO	—	—	1.20	V	Rp = 49.9 Ω, VDD = 3.3 V
Output Current	Io	—	I(nom)	—	mA	VDD = 3.3 V
Output resistance		3000	—	—	Ω	VO = 1.2 V

- Notes: 1. For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditions
2. I(nom) is output current(Ioh) shown in below.  
 Ioh = VDD/(3Rr) = 3.3/(3x475) = 2.32 mA,  
 Ioh x6 = 13.89 mA (Voh @Z: 0.695V @50 Ω),  
 Ioh x2 = 4.63 mA (Voh @Z: 0.232V @50 Ω)

**AC Electrical Characteristics SRC/SRC# Clock (SRC at 0.7V Timing)**

Ta = 0°C to 70°C, VDD = 3.3 V, CL = 2 pF, Rs = 33.2 Ω, Rp = 49.9 Ω

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	Notes
Cycle to cycle jitter	tccs	—	125	—	ps		Note1
Rise time	tr	175	—	700	ps	VO = 0.175 V to 0.525 V	100 MHz
Fall time	tf	175	—	700	ps	VO = 0.175 V to 0.525 V	100 MHz
Clock Duty Cycle		45	50	55	%		100 MHz
SRC clock period(100)		—	9.99	—	ns		
SRC clock period(200)		—	4.99	—	ns		
Cross point(0.7V) voltage	Vcross	0.25	—	0.55	V		100 MHz

- Note: 1. Difference of cycle time between two adjoining cycles.



**DC Electrical Characteristics / 3V66 Buffer (CK409T Type5 Buffer)**

Ta = 0°C to 70°C, VDD = 3.3 V

Item	Symbol	Min	Typ *1	Max	Unit	Test Conditions
Output Voltage	V <sub>OH</sub>	3.1	—	—	V	I <sub>OH</sub> = -1 mA, VDD = 3.3 V
	V <sub>OL</sub>	—	—	50	mV	I <sub>OL</sub> = 1 mA, VDD = 3.3 V
Output Current	I <sub>OH</sub>	—	—	-33	mA	V <sub>OH</sub> = 1.0 V
	I <sub>OL</sub>	30	—	—	mA	V <sub>OL</sub> = 1.95 V

Note: 1. For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditions.

**AC Electrical Characteristics / 3V66 Buffer**

Ta = 0°C to 70°C, VDD = 3.3 V, C<sub>L</sub> = 30 pF

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	Notes
Cycle to cycle jitter	t <sub>CCS</sub>	—	250	—	ps	Fig.1	Note1
3V66 Buffer (3V66 (4:0)) Group Skew	t <sub>skS</sub>	—	0	250	ps	Rising edge @1.5 V to 1.5 V Fig.2	
Slew rate	t <sub>SL</sub>	1.0	—	4.0	V/ns		0.4V to 2.4 V
Clock Period		—	14.998	—	ns		
Clock Duty Cycle		45	50	55	%		
3V66 (4:0) leads 33 MHz PCI		1.5	—	3.5	ns		

Note: 1. Difference of cycle time between two adjoining cycles.

**DC Electrical Characteristics / PCI & PCIF Clock (CK409T Type5 Buffer)**

Ta = 0°C to 70°C, VDD = 3.3 V

Item	Symbol	Min	Typ *1	Max	Unit	Test Conditions
Output Voltage	V <sub>OH</sub>	3.1	—	—	V	I <sub>OH</sub> = -1 mA, VDD = 3.3 V
	V <sub>OL</sub>	—	—	50	mV	I <sub>OL</sub> = 1 mA, VDD = 3.3 V
Output Current	I <sub>OH</sub>	—	—	-33	mA	V <sub>OH</sub> = 1.0 V
	I <sub>OL</sub>	30	—	—	mA	V <sub>OL</sub> = 1.95 V

Note: 1. For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditions.

**AC Electrical Characteristics / PCI & PCIF Clock**

Ta = 0°C to 70°C, VDD = 3.3 V, C<sub>L</sub> = 30 pF

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	Notes
Cycle to cycle jitter	t <sub>ccs</sub>	—	250	—	ps	Fig.1	Note1
PCI Group Skew	tskS	—	0	500	ps	Rising edge @1.5V to 1.5 V Fig.2	
Clock Period		—	29.996	—	ns		
Slew rate	t <sub>SL</sub>	1.0	—	4.0	V/ns		0.4 V to 2.4 V
Clock Duty Cycle		45	50	55	%		

Note: 1. Difference of cycle time between two adjoining cycles.

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**DC Electrical Characteristics / USB & VCH 48MHz Clock  
(CK409T Type3A Buffer)**

Ta = 0°C to 70°C, VDD = 3.3 V

Item	Symbol	Min	Typ *1	Max	Unit	Test Conditions
Output Voltage	V <sub>OH</sub>	3.1	—	—	V	I <sub>OH</sub> = -1 mA, VDD = 3.3 V
	V <sub>OL</sub>	—	—	50	mV	I <sub>OL</sub> = 1 mA, VDD = 3.3 V
Output Current	I <sub>OH</sub>	—	—	-29	mA	V <sub>OH</sub> = 1.0 V
	I <sub>OL</sub>	29	—	—	mA	V <sub>OL</sub> = 1.95 V

Note: 1. For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditions.

**AC Electrical Characteristics / USB & VCH 48MHz Clock**

Ta = 0°C to 70°C, VDD = 3.3 V, C<sub>L</sub> = 20 pF

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	Notes
Cycle to cycle jitter	t <sub>ccs</sub>	—	[350]	—	ps	Fig.1	Note1
Clock Period		—	20.831	—	ns		
Slew rate	t <sub>SL</sub>	1.0	—	2.0	V/ns		0.4 V to 2.4 V
Clock Duty Cycle		45	50	55	%		

Note: 1. Difference of cycle time between two adjoining cycles.

**DC Electrical Characteristics / DOT Clock (CK409T Type3B Buffer)**

Ta = 0°C to 70°C, VDD = 3.3 V

Item	Symbol	Min	Typ *1	Max	Unit	Test Conditions
Output Voltage	V <sub>OH</sub>	3.1	—	—	V	I <sub>OH</sub> = -1 mA, VDD = 3.3 V
	V <sub>OL</sub>	—	—	50	mV	I <sub>OL</sub> = 1 mA, VDD = 3.3 V
Output Current	I <sub>OH</sub>	—	—	-29	mA	V <sub>OH</sub> = 1.0 V
	I <sub>OL</sub>	29	—	—	mA	V <sub>OL</sub> = 1.95 V

Note: 1. For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditions.

**AC Electrical Characteristics / DOT Clock**

Ta = 0°C to 70°C, VDD = 3.3 V, C<sub>L</sub> = 10 pF

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	Notes
Cycle to cycle jitter	t <sub>CCS</sub>	—	350	—	ps	Fig.1	<b>Note1</b>
Clock Period		—	20.831	—	ns		
Slew rate	t <sub>SL</sub>	2.0	—	4.0	V/ns		0.4V to 2.4V
Clock Duty Cycle		45	50	55	%		

Note: 1. Difference of cycle time between two adjoining cycles.

EOL announced Product

**DC Electrical Characteristics / REF Clock (CK409T Type5 Buffer)**

Ta = 0°C to 70°C, VDD = 3.3 V

Item	Symbol	Min	Typ *1	Max	Unit	Test Conditions
Output Voltage	V <sub>OH</sub>	3.1	—	—	V	I <sub>OH</sub> = -1 mA, VDD = 3.3 V
	V <sub>OL</sub>	—	—	50	mV	I <sub>OL</sub> = 1 mA, VDD = 3.3 V
Output Current	I <sub>OH</sub>	—	—	-33	mA	V <sub>OH</sub> = 1.0 V
	I <sub>OL</sub>	30	—	—	mA	V <sub>OL</sub> = 1.95 V

Note: 1. For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditions.

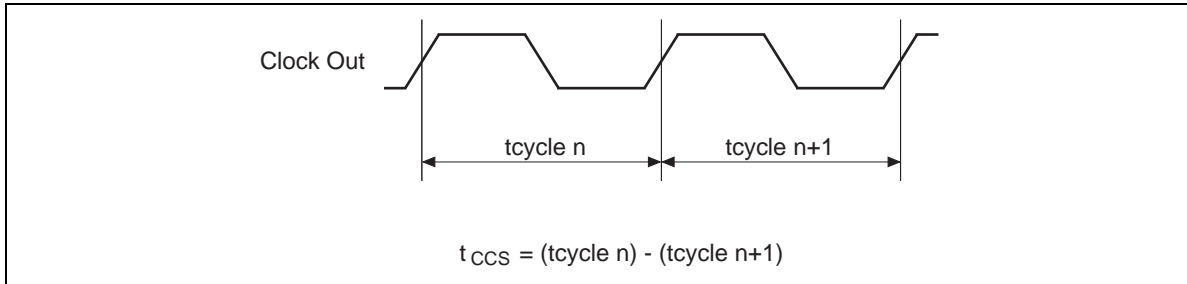
**AC Electrical Characteristics / REF Clock**

Ta = 0°C to 70°C, VDD = 3.3 V, C<sub>L</sub> = 30 pF

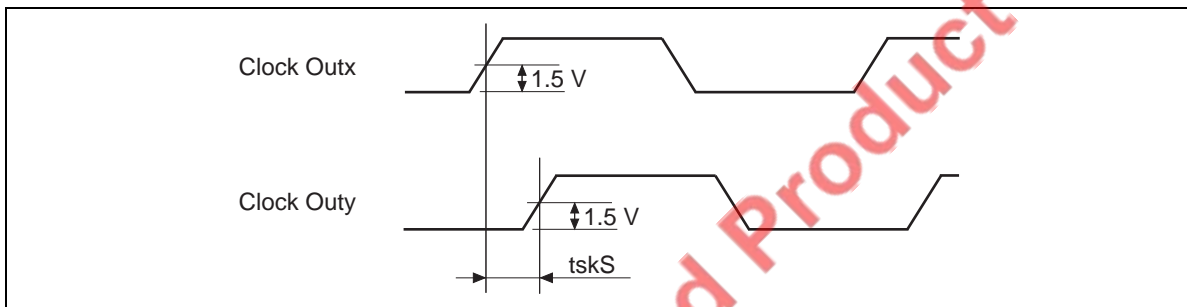
Item	Symbol	Min	Typ	Max	Unit	Test Conditions	Notes
Cycle to cycle jitter	t <sub>CCS</sub>	—	1000	—	ps	Fig.1	<b>Note1</b>
Clock Period		—	69.841	—	ns		
Slew rate	t <sub>SL</sub>	1.0	—	4.0	V/ns		0.4 V to 2.4 V
Clock Duty Cycle		45	50	55	%		

Note: 1. Difference of cycle time between two adjoining cycles.

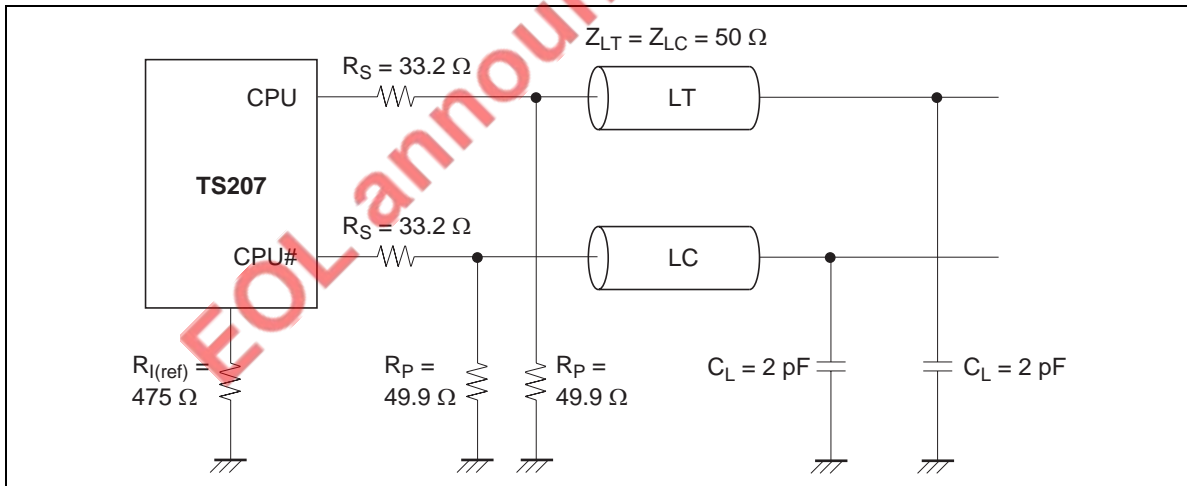
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**Fig.1 Cycle to Cycle Jitter (3.3V Single Ended Clock Output)**



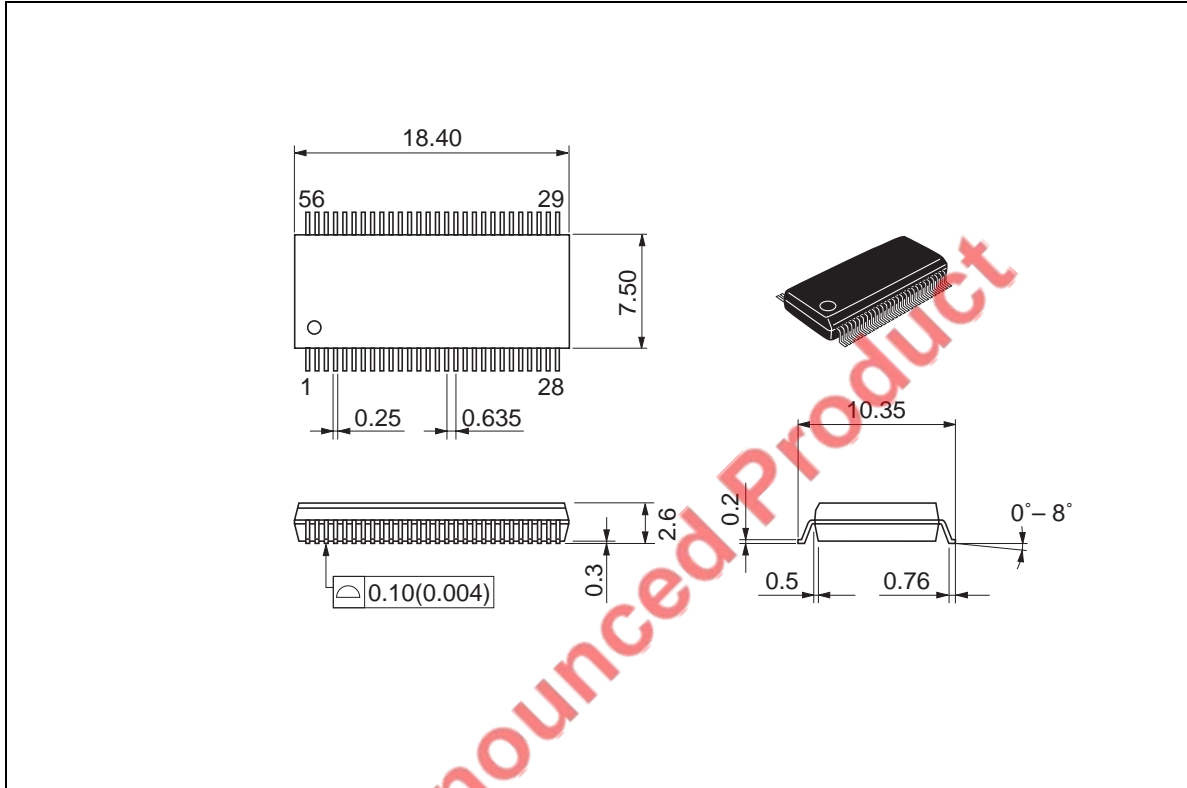
**Fig.2 Output Clock Skew (3.3V Single Ended Clock Output)**



**Fig.3 Load Circuit for CPU/CPU#**

Package Dimensions

Unit : mm



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